

Appl. No. 09/843,630
Amendment C
August 17, 2005

REMARKS

Applicant respectfully requests reconsideration of the prior art rejections set forth by the Examiner under 35 U.S.C. § 102 in light of the newly cited United States patent number 6,306,680. In order to highlight the distinctions between the presently claimed invention and the prior art, Applicant has further modified the independent claims to specify that there are no electrical conductors on the side of the chip opposite the side where all the electrodes are formed. The prior art cited by the Examiner actually teaches away from the presently claimed invention wherein electrical conductor 112 and contact 148 are located on a side of the chip opposite the side at which the electrodes are formed.

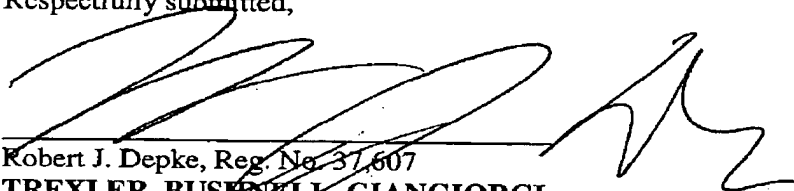
In accordance with the prior art, it would be impossible to achieve the presently claimed invention wherein a pseudo-wafer is formed by identifying good semiconductor chips and placing them on an adhesive member in order to provide protective resin around the sides of the chips and wherein the resin and the side of the chip opposite the electrodes are ground down to a common level as also specify the claims. Accordingly, in light of the foregoing, Applicant respectfully submits that the prior art references of record, whether considered alone, or in combination, fail to teach or suggests Applicants presently claimed invention. As noted above, the side reference actually teaches away from the presently claimed invention.

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Applicant respectfully submits that all claims now stand in condition for allowance.

Respectfully submitted,

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